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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/696,198	10/28/2003	Chien-Ping Huang	60173 (71987)	7288
7590 05/17/2006			EXAMINER	
Mr. Steven M. Jensen			TRINH, HOA B	
Mr. Peter F. Corless EDWARDS & ANGELL, LLP			ART UNIT	PAPER NUMBER
101 Federal Street			2814	
Boston, MA 02110			DATE MAILED: 05/17/2006	

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)				
055 4-45 0	10/696,198	HUANG, CHIEN-PING				
Office Action Summary	Examiner	Art Unit				
	Vikki H. Trinh	2814				
The MAILING DATE of this communication appeared for Reply	ppears on the cover sheet with the c	correspondence address				
A SHORTENED STATUTORY PERIOD FOR REP THE MAILING DATE OF THIS COMMUNICATION - Extensions of time may be available under the provisions of 37 CFR 1 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a re - If NO period for reply is specified above, the maximum statutory perio - Failure to reply within the set or extended period for reply will, by statu Any reply received by the Office later than three months after the mail earned patent term adjustment. See 37 CFR 1.704(b).	136(a). In no event, however, may a reply be tireply within the statutory minimum of thirty (30) day d will apply and will expire SIX (6) MONTHS from the cause the application to become ABANDONE	nely filed rs will be considered timely. I the mailing date of this communication. ID (35 U.S.C. § 133).				
Status						
1) Responsive to communication(s) filed on 13	February 2006.					
3) Since this application is in condition for allow						
Disposition of Claims						
4) ☐ Claim(s) 1-8 is/are pending in the application 4a) Of the above claim(s) is/are withdr 5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) 1-8 is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) are subject to restriction and	awn from consideration.					
Application Papers						
9) ☐ The specification is objected to by the Examination 10) ☑ The drawing(s) filed on 28 October 2003 is/an Applicant may not request that any objection to the Replacement drawing sheet(s) including the correction 11) ☐ The oath or declaration is objected to by the I	re: a) accepted or b) objected or b objected or b objected or b objected or abeyance. Seetion is required if the drawing(s) is objection is required if the drawing(s) is objection.	e 37 CFR 1.85(a). sjected to. See 37 CFR 1.121(d).				
Priority under 35 U.S.C. § 119						
a) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority docume 2. Certified copies of the priority docume 3. Copies of the certified copies of the priority docume application from the International Bure * See the attached detailed Office action for a list	nts have been received. nts have been received in Applicat iority documents have been receive au (PCT Rule 17.2(a)).	ion No ed in this National Stage				
Attachment(s)	4) 🔲 Intensions Commune	(PTO 413)				
 Notice of References Cited (PTO-892) Notice of Draftsperson's Patent Drawing Review (PTO-948) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/0 Paper No(s)/Mail Date 	4) Interview Summary Paper No(s)/Mail D 5) Notice of Informal F 6) Other:					

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DETAILED ACTION

Claims Status

1. Claims 1-8 are pending in this present application. Claims 9-18 have been canceled in the amendment filed on 08/02/05.

Claim Rejections - 35 USC § 102

2. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (a) the invention was known or used by others in this country, or patented or described in a printed publication in this or a foreign country, before the invention thereof by the applicant for a patent.
- 3. Claims 1-4, 6-8 are rejected under 35 U.S.C. 102(a) as being anticipated by Admitted Prior Art (APA), figures 1-3.

APA discloses a multi-chip package device with a heat sink, comprising a chip carrier 20 (fig. 2); at least one first chip 11 (fig. 1) or 21 (fig. 2) mounted on and electrically connected to a surface of the chip carrier 20 (fig. 2); at least one semiconductor package 1,15 (fig. 1) or 22 (fig. 2) mounted on and electrically connected to the surface of the chip carrier 10 (fig. 1) or 20 (fig. 2); and the heat sink 24 (fig. 2) mounted via an adhesion layer 23 (fig. 2) on a surface of the first chip 21 (fig. 2) and a surface of the semiconductor package 22 (fig. 2) that are opposite to surfaces of the first chip 21 (fig. 2) and the semiconductor package 22 (fig. 2) mounted on the chip carrier 20 (fig. 2). APA does teach that at least one hollow part extending through the heat sink is formed at an area of the heat sink free of contact with the first chip and the semiconductor package to release thermal stresses from the heat sink through the at least one hollow part that remains hollow. See attachment.

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As to claim 2, APA teaches that the semiconductor package 2 (fig. 2) is a flip-chip ball grid array package (specification, page 3, line 11).

As to claim 3, APA teaches that the first chip 11 (fig. 1) is a graphic chip.

As to claim 4, APA teaches that the first chip 11 (fig. 1) is a graphic processing unit.

As to claim 6, APA teaches that the first chip 21 (fig. 2) is mounted at the center of the chip carrier 20 (fig. 2), and the semiconductor package 2 (fig. 2) is mounted at a position on the chip carrier 20 (fig. 2) corresponding to a corner of the heat sink 24 (fig. 2).

As to claim 7, APA teaches that at least one pair of the semiconductor packages 22 (fig. 2) are mounted on the chip carrier 20 (fig. 2), and the hollow part (fig. 2) of the heat sink 24 (fig. 2) is located between the semiconductor packages.

As to claim 8, at least one symmetrical pair (fig. 2) of the hollow parts (fig. 2) are formed through the heat sink 24(fig. 2).

Claim Rejections - 35 USC § 103

- 4. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 5. The factual inquiries set forth in *Graham* v. *John Deere Co.*, 383 U.S. 1, 148 USPQ 459 (1966), that are applied for establishing a background for determining obviousness under 35 U.S.C. 103(a) are summarized as follows:

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1. Determining the scope and contents of the prior art.

- 2. Ascertaining the differences between the prior art and the claims at issue.
- 3. Resolving the level of ordinary skill in the pertinent art.
- 4. Considering objective evidence present in the application indicating obviousness or nonobviousness.

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- 6. This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(e), (f) or (g) prior art under 35 U.S.C. 103(a).
- 7. Claim 5 is rejected under 35 U.S.C. 103(a) as being unpatentable over Admitted Prior Art (APA), figures 1-3, in view of Behlen et al. (hereinafter Behlen) (5,598,033).

APA discloses the invention substantially as claimed. However, APA and HO do not explicitly teach that the semiconductor package is a Random Access Memory (RAM) unit.

Behlen discloses an analogous BGA package 300 (fig. 3) having a carrier 338, solder bumps 314 (fig. 3), and chip 310 (fig. 3), wherein the package is a volatile RAM (col. 1, line 13).

Therefore, it would have been obvious to one of ordinary skills in the art at the time the invention was made to modify the invention of APA with a RAM, as taught by Behlen, as merely a matter of selecting a type of device for packaging.

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Response to Arguments

8. Applicant's arguments filed 02/28/06have been fully considered but they are moot in view of the new rejection. Applicants have not yet overcome the art rejection because the claims are still too broad.

Conclusion

- 9. Any inquiry concerning this communication or earlier communications from the Examiner should be directed to Vikki Trinh whose telephone number is (571) 272-1719. The Examiner can normally be reached from Monday-Friday, 9:00 AM 5:30 PM Eastern Time. If attempts to reach the examiner by telephone are unsuccessful, the Examiner's supervisor, Mr. Wael Fahmy, can be reached at (571) 272-1705. The office fax number is 703-872-9306.
- 10. Any request for information regarding to the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Also, status information for published applications may be obtained from either Private PAIR or Public Pair. In addition, status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. If you have questions pertaining to the Private PAIR system, please contact the Electronic Business Center (EBC) at 866-217-9197 (toll free).
- 11. Lastly, paper copies of cited U.S. patents and U.S. patent application publications will cease to be mailed to applicants with Office actions as of June 2004. Paper copies of foreign patents and non-patent literature will continue to be included with office actions. These cited U.S. patents and patent application publications are available for download via the Office's PAIR. As an alternate source, all U.S. patents and patent application publications are available

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on the USPTO web site (www.uspto.gov), from the Office of Public Records and from commercial sources. Applicants are referred to the Electronic Business Center (EBC) at http://www.uspto.gov/ebc/index.html or 1-866-217-9197 for information on this policy. Requests to restart a period for response due to a missing U.S. patent or patent application publications will not be granted.

Vikki Trinh, Patent Examiner AU 2814

HOWARD WEISS
REIMARY EXAMINER

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Attachment

22400

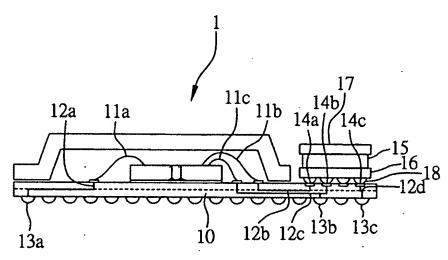


FIG. 1 (PRIOR ART)

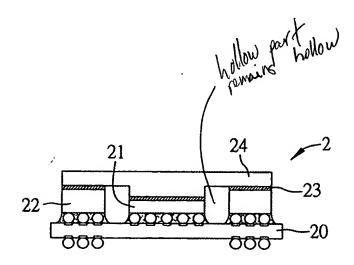


FIG. 2 (PRIOR ART)